FIG. 1

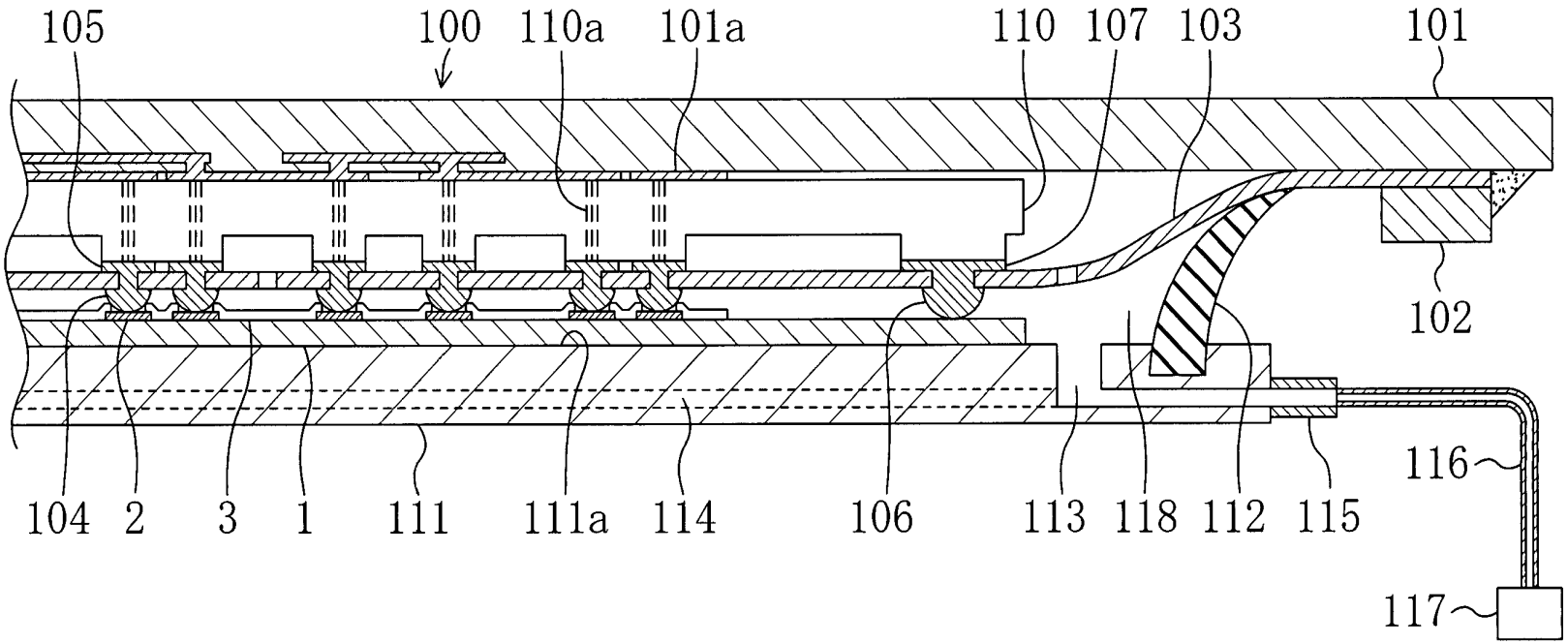
105
100
110a
101a
110
107
103
101
102
104
2
3
1
111
111a
114
106
113
118
112
115
116
117

FIG. 2

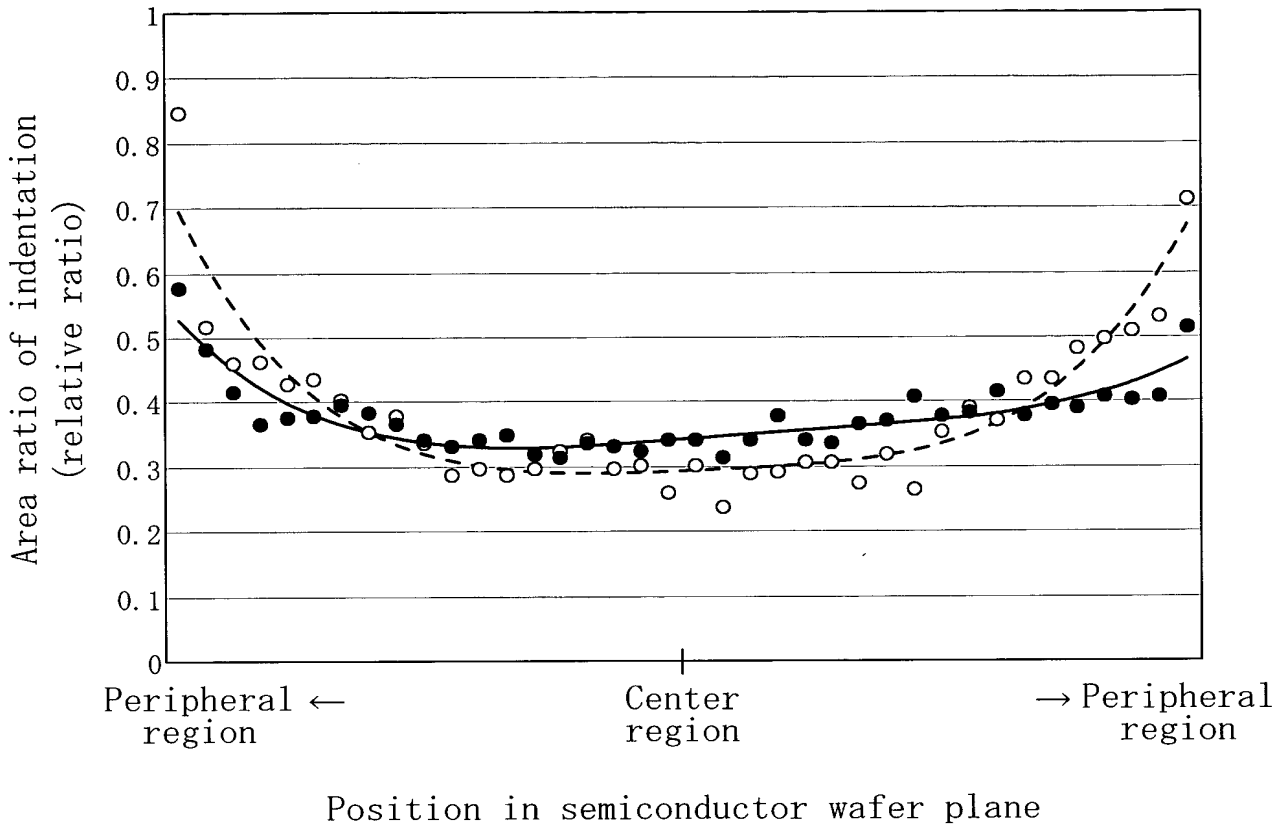
Area ratio of indentation
(relative ratio)
1
0.9
0.8
0.7
0.6
0.5
0.4
0.3
0.2
0.1
0
Peripheral ←
region
Center
region
→ Peripheral
region
Position in semiconductor wafer plane

FIG. 3A

FIG. 3B

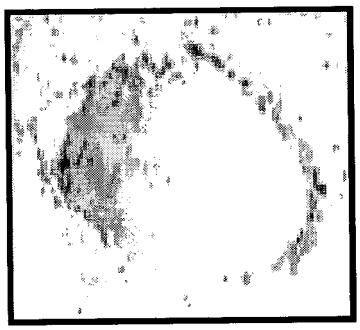

FIG. 3C

FIG. 4

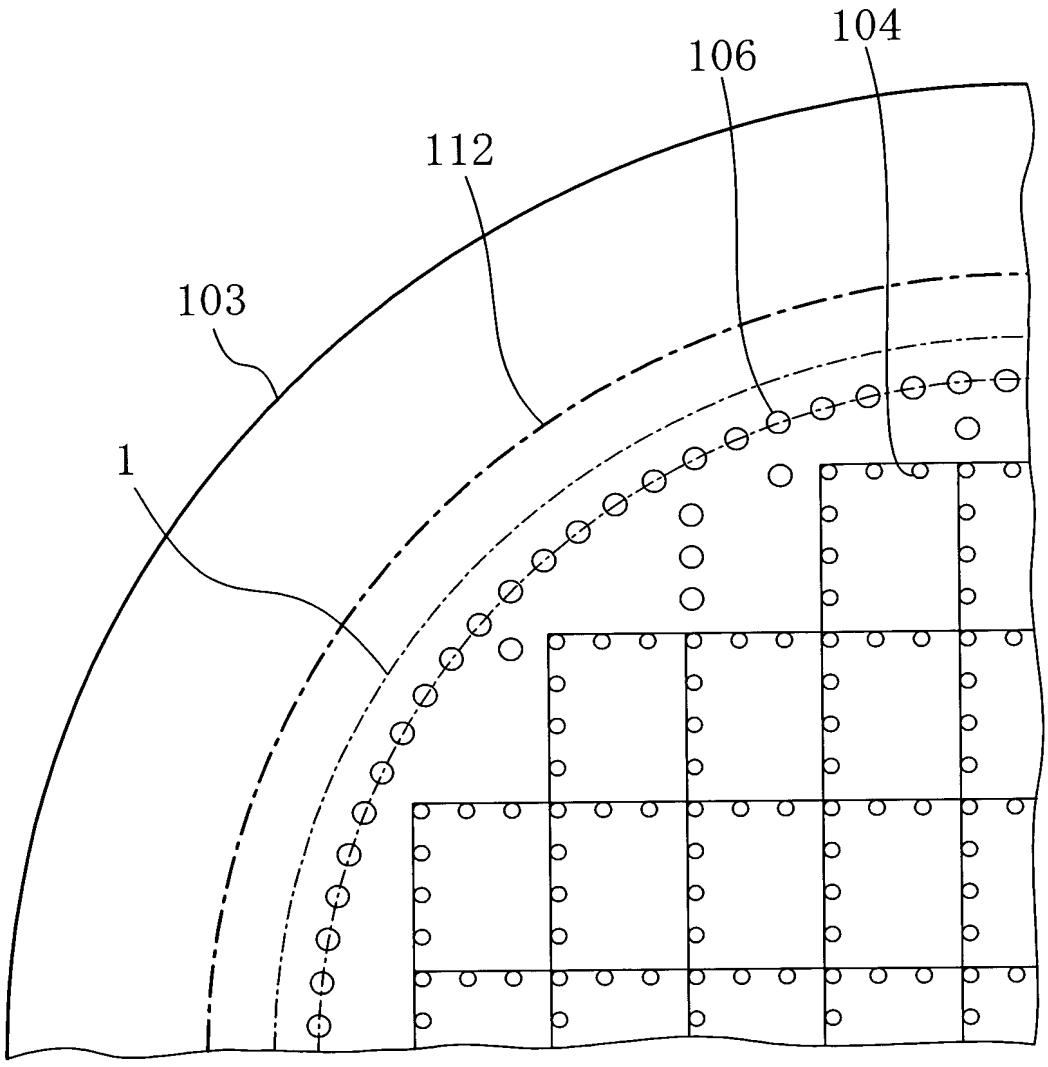

FIG. 5

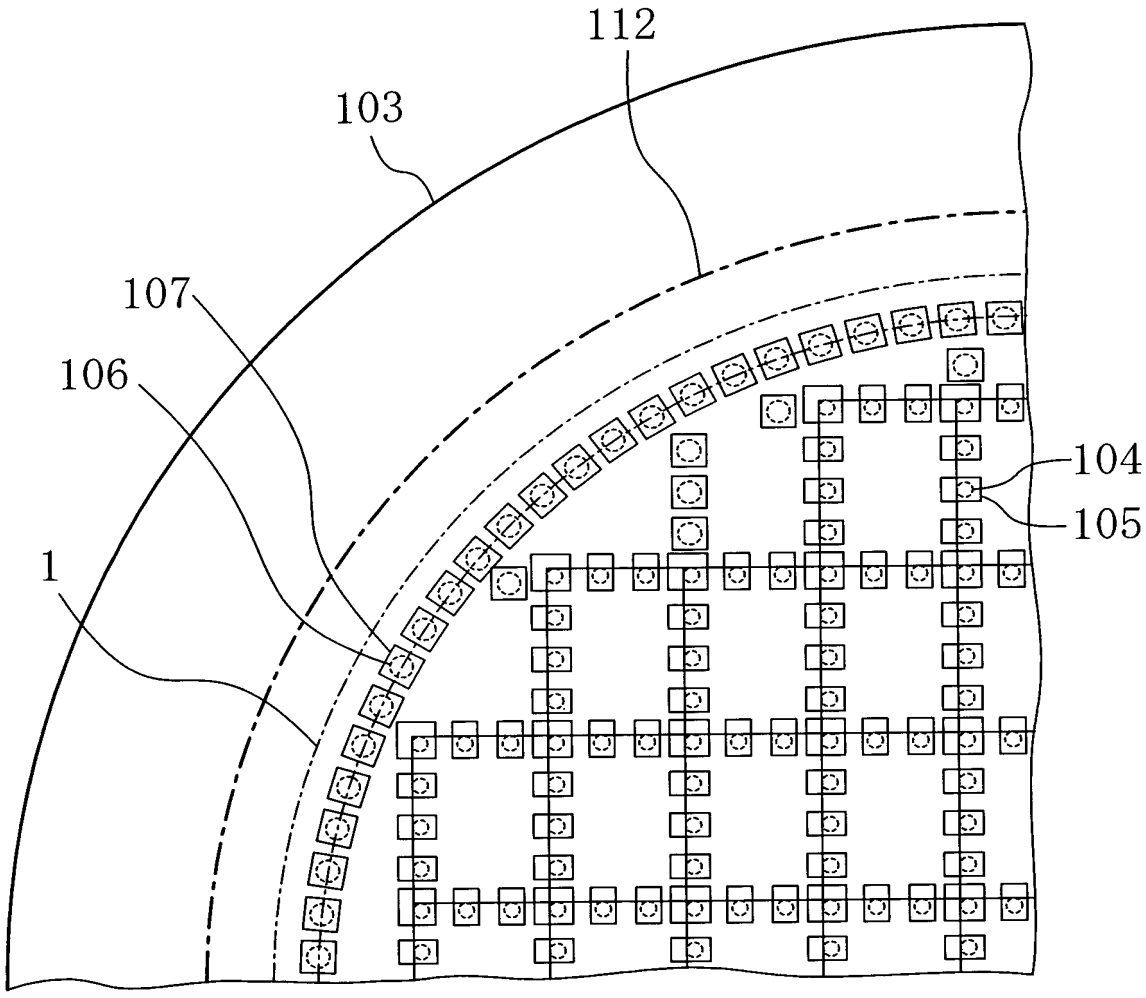

FIG. 6

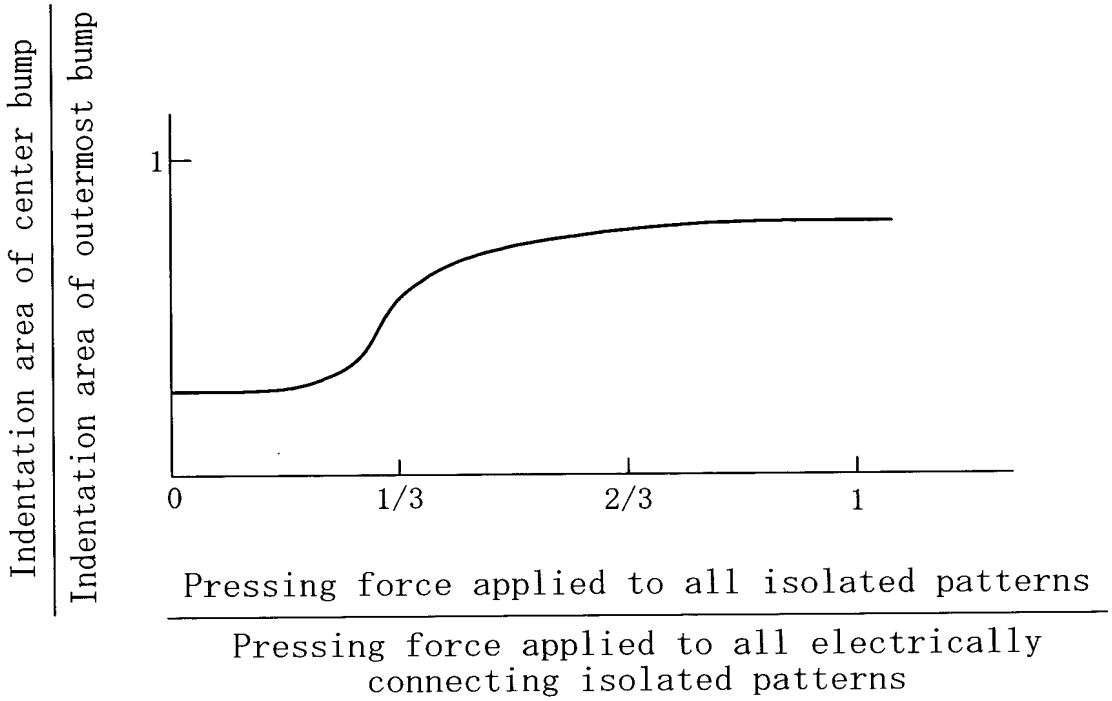
Indentation area of center bump
Indentation area of outermost bump
1
0
1/3
2/3
1
Pressing force applied to all isolated patterns
Pressing force applied to all electrically connecting isolated patterns

FIG. 7

PRIOR ART

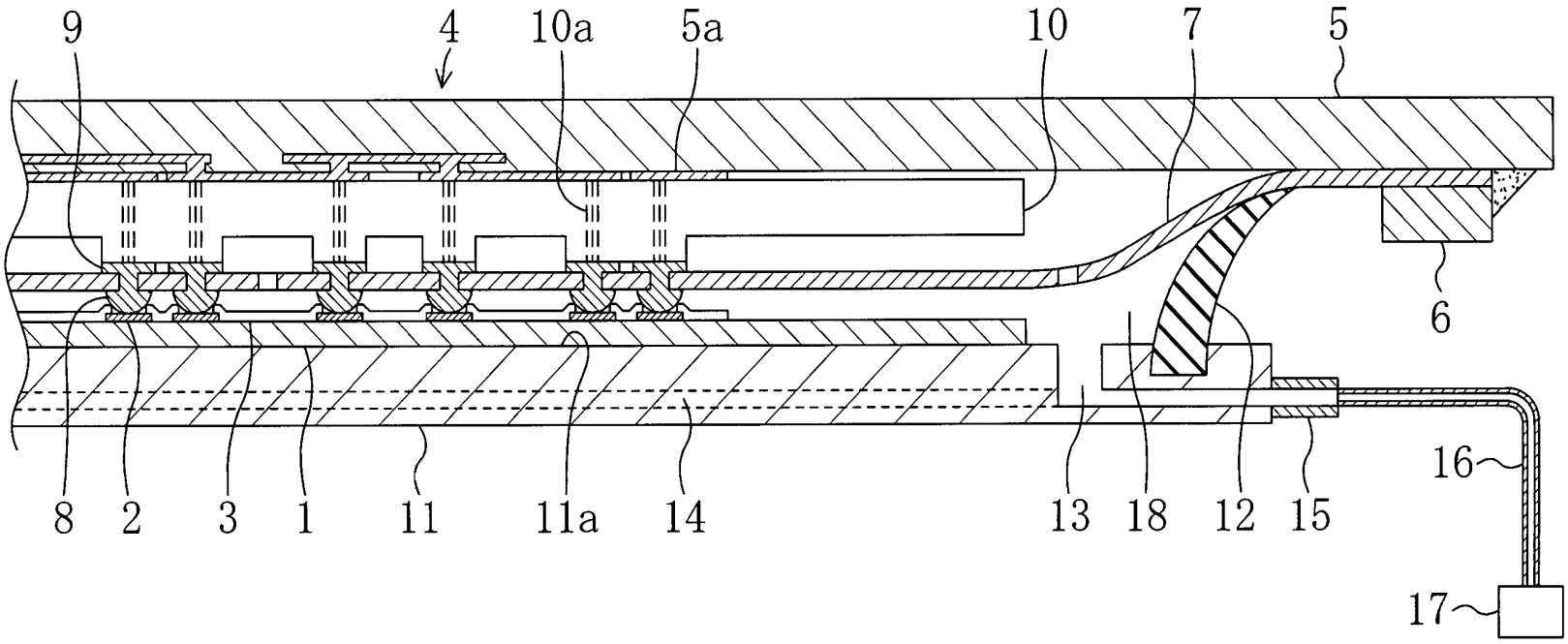

FIG. 8
PRIOR ART

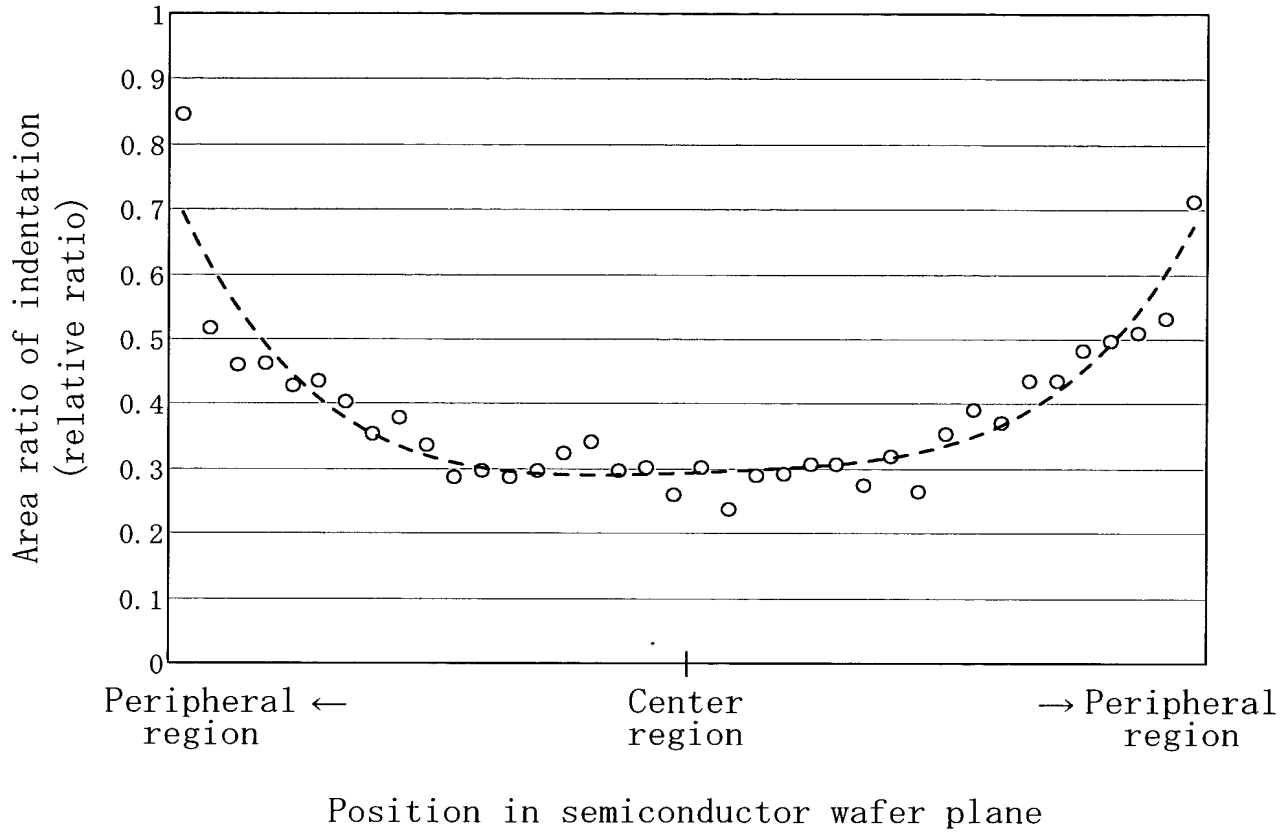

FIG. 9A
PRIOR ART

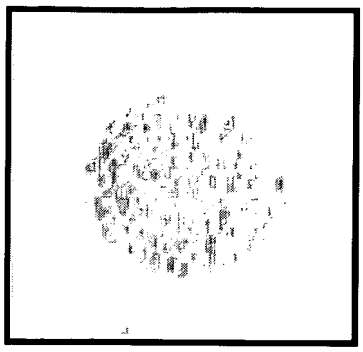

FIG. 9B
PRIOR ART

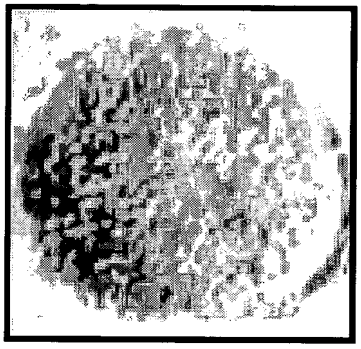

FIG. 9C
PRIOR ART